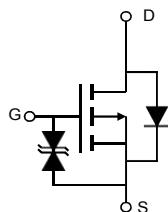
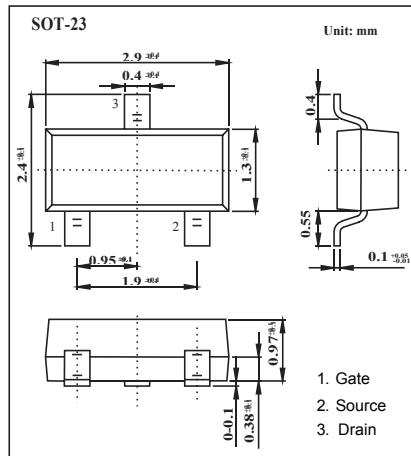


P-Channel MOSFET**RC3415P****■ Features**

- V_{DS} (V) = -20V
- I_D = -4A (V_{GS} = -4.5V)
- $R_{DS(ON)} < 40m\Omega$ (V_{GS} = -4.5V)
- $R_{DS(ON)} < 60m\Omega$ (V_{GS} = -2.5V)
- $R_{DS(ON)} < 100m\Omega$ (V_{GS} = -1.8V)
- ESD Rating: 2000V HBM

**■ Absolute Maximum Ratings $T_a = 25^\circ C$**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 10	
Continuous Drain Current $T_a = 25^\circ C$	I_D	-4	A
		-3.5	
Pulsed Drain Current	I_{DM}	-30	A
Power Dissipation (Note.1) $T_a = 25^\circ C$	P_D	1.5	W
		1	
Thermal Resistance.Junction- to-Ambient $t \leq 10s$ Steady-State	R_{thJA}	80	$^\circ C/W$
		100	
Thermal Resistance.Junction- to-Lead	R_{thJL}	52	$^\circ C$
Junction Temperature	T_J	150	
Junction Storage Temperature Range	T_{stg}	-55 to 150	

Note.1: The power dissipation P_D is based on $T_{J(MAX)}=150^\circ C$, using $\leq 10s$ junction-to-ambient thermal resistance.

P-Channel MOSFET**RC3415P**■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DSS}	$I_D=-250 \mu\text{A}, V_{GS}=0\text{V}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}$			-1	μA
		$V_{DS}=-20\text{V}, V_{GS}=0\text{V}, T_J=55^\circ\text{C}$			-5	
Gate-Body leakage current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 10\text{V}$			± 10	uA
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS} I_D=-250 \mu\text{A}$	-0.5		-1.0	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-4.5\text{V}, I_D=-4\text{A}$			40	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-4\text{A}, T_J=125^\circ\text{C}$			62	
		$V_{GS}=-2.5\text{V}, I_D=-4\text{A}$			60	
		$V_{GS}=-1.8\text{V}, I_D=-2\text{A}$			100	
On state drain current	$I_{D(\text{ON})}$	$V_{GS}=-4.5\text{V}, V_{DS}=-5\text{V}$	-30			A
Forward Transconductance	g_{FS}	$V_{DS}=-5\text{V}, I_D=-4\text{A}$		20		S
Input Capacitance	C_{iss}	$V_{GS}=0\text{V}, V_{DS}=-10\text{V}, f=1\text{MHz}$		1450		pF
Output Capacitance	C_{oss}			205		
Reverse Transfer Capacitance	C_{rss}			160		
Gate resistance	R_g	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		6.5		Ω
Total Gate Charge	Q_g	$V_{GS}=-4.5\text{V}, V_{DS}=-10\text{V}, I_D=-4\text{A}$		17.2		nC
Gate Source Charge	Q_{gs}			1.3		
Gate Drain Charge	Q_{gd}			4.5		
Turn-On DelayTime	$t_{d(\text{on})}$	$V_{GS}=-4.5\text{V}, V_{DS}=-10\text{V}, R_L=2.5\Omega, R_{GEN}=3\Omega$		9.5		ns
Turn-On Rise Time	t_r			17		
Turn-Off DelayTime	$t_{d(\text{off})}$			94		
Turn-Off Fall Time	t_f			35		
Body Diode Reverse Recovery Time	t_{rr}	$I_F=-4\text{A}, dI/dt=100\text{A}/\mu\text{s}$		31		nC
Body Diode Reverse Recovery Charge	Q_{rr}			13.8		
Maximum Body-Diode Continuous Current	I_s				-2.2	A
Diode Forward Voltage	V_{SD}	$I_s=-1\text{A}, V_{GS}=0\text{V}$		-0.78	-1	V

■ Marking

Marking	3415T.
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P-Channel MOSFET

RC3415P

■ Typical Characteristics

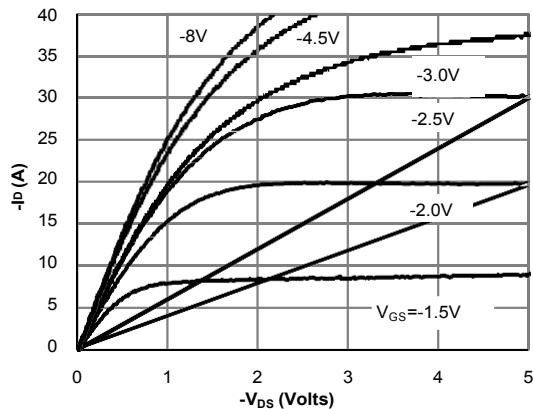


Fig 1: On-Region Characteristics

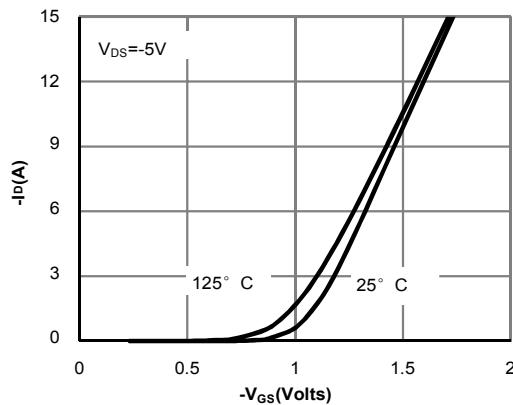


Figure 2: Transfer Characteristics

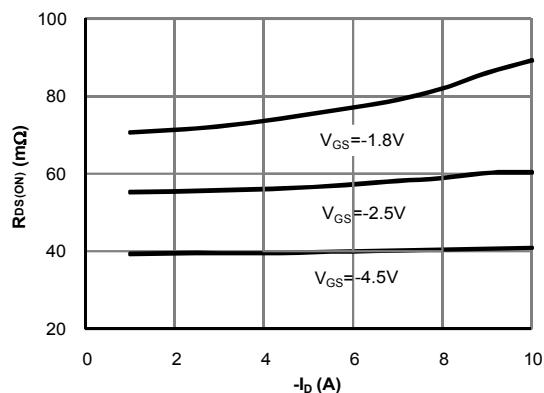


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

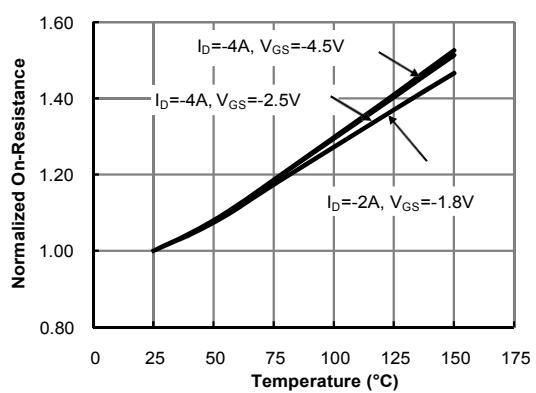


Figure 4: On-Resistance vs. Junction Temperature

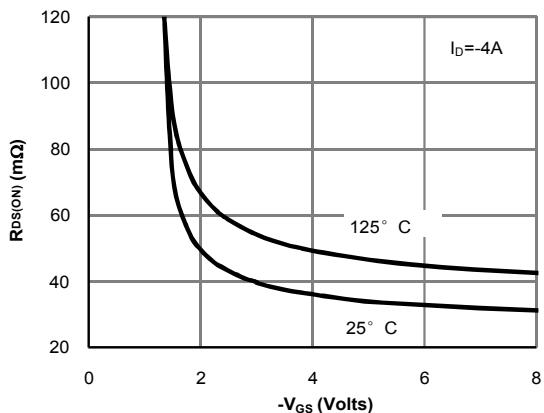


Figure 5: On-Resistance vs. Gate-Source Voltage

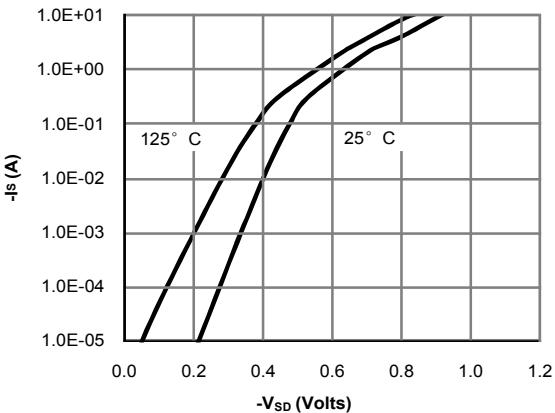


Figure 6: Body-Diode Characteristics

P-Channel MOSFET

RC3415P

■ Typical Characteristics

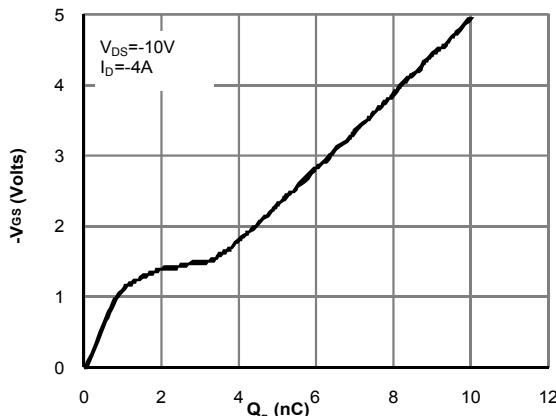


Figure 7: Gate-Charge Characteristics

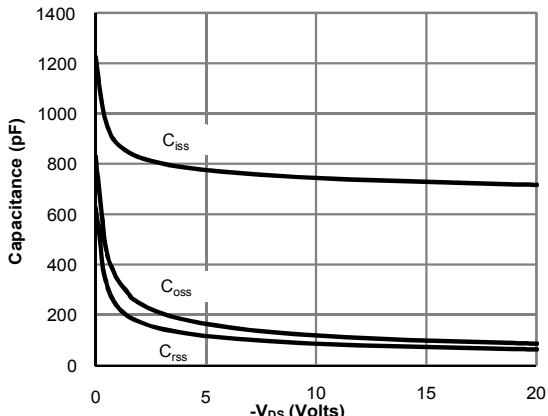


Figure 8: Capacitance Characteristics

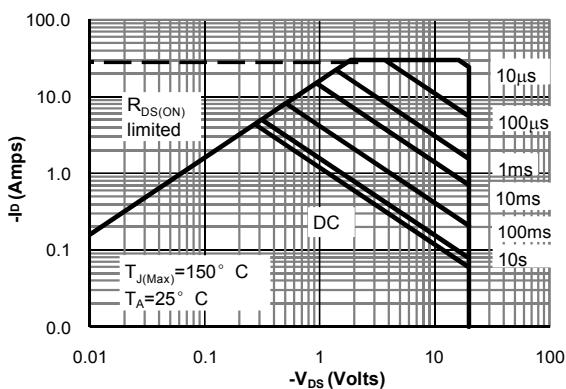


Figure 9: Maximum Forward Biased Safe Operating Area

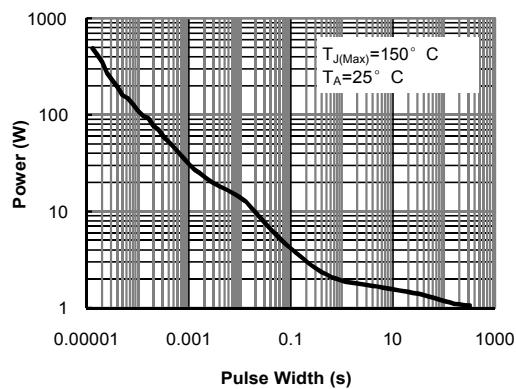


Figure 10: Single Pulse Power Rating Junction-to-Ambient

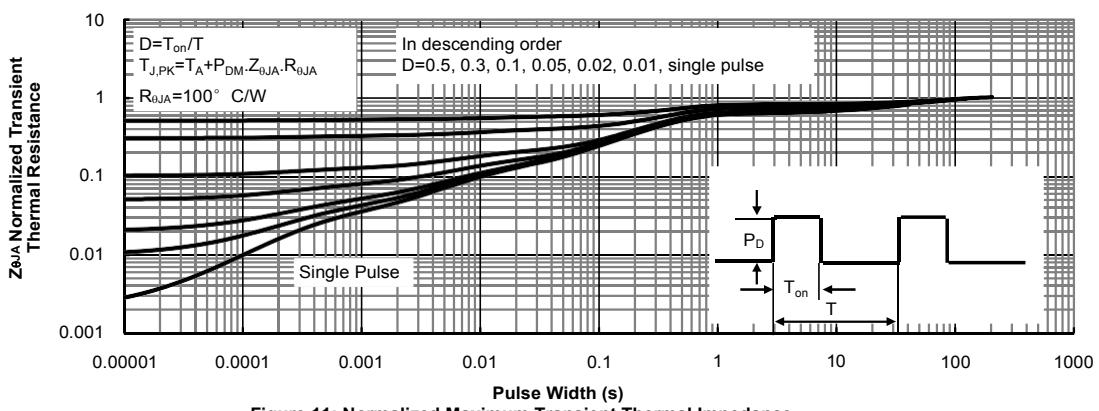


Figure 11: Normalized Maximum Transient Thermal Impedance